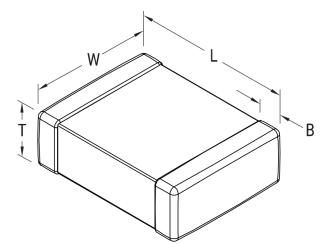


CKC33C822GEGAC7210

KC-LINK Comm COG, Ceramic, 8200 pF, 2%, 1200 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 3640



Click here for the 3D model.

Dimensions	
Chip Size	3640
L	9.3mm +/-0.6mm
W	10.2mm +/-0.4mm
т	2mm +/-0.20mm
В	1.27mm +/-0.4mm

	Packaging Specifications	ckaging Specifications	
	Packaging	T&R, 330mm, Plastic Tape	
	Packaging Quantity	1000	
	5 5		

General Information	
Series	KC-LINK Comm COG
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	790 mg
Shelf Life	78 Weeks
MSL	1

Specifications				
Capacitance	8200 pF			
Measurement Condition	1 kHz 1.0Vrms			
Capacitance Tolerance	2%			
Voltage DC	1200 VDC			
Dielectric Withstanding Voltage	1440 VDC			
Temperature Range	-55/+150°C			
Temperature Coefficient	COG			
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms			
Dissipation Factor	0.1% 1 kHz 1.0Vrms			
Aging Rate	0% Loss/Decade Hour			
Insulation Resistance	100 GOhms			

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.